# 504087084 11/08/2016

# PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT4133752

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
YONGJUN JEFF HU	03/31/1999

## **RECEIVING PARTY DATA**

Name:	MICRON TECHNOLOGY, INC.	
Street Address:	8000 SOUTH FEDERAL WAY	
City:	BOISE	
State/Country:	IDAHO	
Postal Code:	83707	

# **PROPERTY NUMBERS Total: 6**

Property Type	Number
Patent Number:	6781365
Patent Number:	6870380
Patent Number:	7046029
Patent Number:	6646456
Patent Number:	6518181
Patent Number:	6765398

## **CORRESPONDENCE DATA**

**Fax Number:** (602)244-3169

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

**Phone:** 6022443574

Email: patents@onsemi.com

Correspondent Name: SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC

Address Line 1: 5005 E. MCDOWELL ROAD

Address Line 2: MAILDROP A700

Address Line 4: PHOENIX, ARIZONA 85008

ATTORNEY DOCKET NUMBER:	APT1998-0210CONS_DIVS	
NAME OF SUBMITTER:	SHARRON CASTILLO	
SIGNATURE:	/Sharron Castillo/	
DATE SIGNED:	11/08/2016	

PATENT 504087084 REEL: 040257 FRAME: 0570

# **Total Attachments: 1**

 $source = APT1998-0210Cons-Divs\_2061108\_Assignment\_InvntrMicron\#page1.tif$ 

PATENT REEL: 040257 FRAME: 0571 Application No.: Unknown Client Code: MICRON.081A Filing Date: Herewith Page 1

#### ASSIGNMENT

WHEREAS, I, Yongjun Jeff Hu, a citizen of the People's Republic of China, residing at 2571 South Culpeper Avenue, Boise, Idaho 83709, have invented certain new and useful improvements in a CONDUCTIVE MATERIAL FOR INTEGRATED CIRCUIT FABRICATION for which I have executed an application for Letters Patent in the United States, on even date herewith;

AND WHEREAS, Micron Technology, Inc. (hereinafter "ASSIGNEE"), a Delaware Corporation, with its principal place of business at 8000 South Federal Way, P.O. Box 6, Boise, Idaho 83707-0006, desires to acquire the entire right, title, and interest in and to the said improvements and the said Application:

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to me in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, I, the said inventor, do hereby acknowledge that I have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title, and interest throughout the world in, to and under the said improvements, and the said application and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions and applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and I hereby authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I HEREBY covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

IN TESTIMONY WHEREOF, I hereunto set my hand and seal this 3/15 day of March 1999 Yongjun Jeff Hu STATE OF Idaho ss.

On Mar. 31, 1999, before me, Susanne R. Jerome, personally appeared Yongjun Jeff Hu, personally known to me (or proved to me on the basis of satisfactory evidence) to be the person whose name is subscribed to the within instrument, and acknowledged to me that it executed the same in it authorized capacity, and that by it signature on the instrument the person, or the entity upon behalf of which the person acted, executed the instrument.

ESS my hand and official seal.

COUNTY OF Ada

KK\MICK@ 081AURK-1146.DOC:sb

**RECORDED: 11/08/2016** 

PATENT REEL: 040257 FRAME: 0572